



Product/Process Change Notice

PCN # P-2004-0014

Date: 2020/11/13

Dear Customer:

Please be informed that Macronix is going to implement a change on the carrier tray for the 63BGA package.

Based on past experience and experiment result, the new tray with a chamfering (sloped sidewall) design modification, can avoid the risk of the BGA being misplaced and be jammed/damaged by the other stacked tray due to the current steep sidewall design of the current tray. This advantage can assist the customer with a smoother operation at the SMT line.

Other than the pocket sidewall redesign, there is no change on the tray material, dimension, or matrix compared to the original tray design.

The detailed information about this change is described in the following pages.

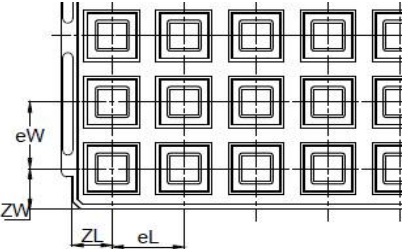
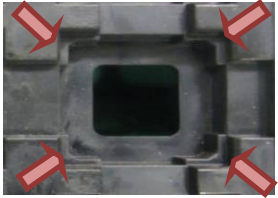
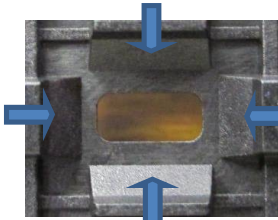
If you have any questions, concerns, or requests about this change, please contact your local Macronix Sales Representatives within 30 days, otherwise Macronix will assume customer received the PCN with no comments and the change is acceptable to the customer. Macronix follows JEDEC J-STD-046, it stipulates: ".....Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change".



Thank you.

Macronix International Co., Ltd.

旺宏電子股份有限公司

(Note: For the customers who receive Macronix PCNs via distributors, Macronix will assist the distributors to convey the PCNs to the customers. It is each distributor's responsibility to communicate and track the responses of each customers and report back to Macronix, the distributor shall assume full responsibilities if failed to do so.)

<p>PCN No.: P-2004-0014</p>	<p>Issue Date : 2020/11/13</p>
<p>Subject: Change of carrier tray spec. for 63BGA package</p>	
<p>Change Category: Carrier Tray Spec.</p>	
<p>Affected Products: All Macronix carrier trays with 63 BGA</p>	
<p>Reason of Change: To avoid the risk of IC being misplaced and jammed/damaged.</p>	
<p>Before Change :</p>	<p>After Change :</p>
<p>1) <u>Outline.(mm)</u> → Follow JEDEC' spec. (L*W*H) / (322.6x135.9x7.62)</p> <p>2). <u>Material:</u> → PPE Tray.</p> <p>3). <u>Matrix:</u> → X*Y : 22*10</p> <p>4). <u>Dimension:(mm) :</u> Please reference below illustration. 4-1). Pocket Pitch X value (eW): →12.80 +/-0.13 4-2). Pocket Pitch Y value (eL): →14.00 +/-0.13 4-3). Pocket center to tray edge X value (ZL): → 10.35 +/-0.13 4-4). Pocket center to tray edge Y value (ZW): →10.50 +/-0.13</p>  <p>5). <u>Pocket design</u> → IC positioning by pocket corner. (Top view of pocket)</p>  <p><u>No chamfering design.</u></p> <p>Pocket cross-section view</p>	<p>1). <u>Outline.(mm)</u> → No change.</p> <p>2). <u>Material:</u> → No change.</p> <p>3). <u>Matrix: :</u> → No change.</p> <p>4). <u>Dimension,(mm)</u> → No change.</p> <p>5). <u>Pocket design.</u> → IC positioning by pocket edge. (Top view of pocket)</p>  <p><u>Pocket chamfering design</u></p> <p>Pocket cross-section view</p>

<p style="text-align: center;">X-Axis Y-Axis</p>  <p>Note: No chamfering design (steep sidewalls) the pocket is easier to cause misplacement and damage the IC</p>	<p style="text-align: center;">X-Axis Y-Axis</p>  <p>Note: with chamfering design (sloped sidewalls) the tray pocket can avoid IC being misplaced and jammed/damaged.</p>
<p>Product identification: No change</p>	
<p>Assessment Result: Reliability: The new tray design has passed dimension inspection / bake test. Green product: The new tray meets the RoHS requirement (Tray material no change)</p>	
<p>Implementation Schedule: 2021/1/1. (Note: An overlap period of mixture of old and new carrier tray is expected until the old materials are depleted.)</p>	

MPN's Affected

[MX30LF1G08AA-XKI](#)

[MX30LF1G18AC-XKI](#)

[MX30UF2G18AC-XKI](#)

[MX30UF4G18AB-XKI](#)

[MX60LF8G18AC-XKI](#)